



Title of Change:	WL-CSP package fab site transfer to the ON Semiconductor Niigata, Japan facility for the LC051281XA product.				
Proposed first ship date:	31 January 2018 or earlier after customer approval				
Contact information:	Contact your local ON Semiconductor Sales Office or <Hiroshi.Kojima@onsemi.com>				
Samples:	Contact your local ON Semiconductor Sales Office				
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Satoru.Fujinuma@onsemi.com>.				
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.				
Change Part Identification:	Products manufactured at Niigata will be printed Date Code from 1745 on shipping MPN label.				
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____				
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____				
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Gunma, Japan, ON Niigata, Japan <input type="checkbox"/> External Foundry/Subcon site(s)				
Description and Purpose:	To continuously supply products and increase our supply capacity to support increased demand; the Wafer Level Chip Size Package (WL-CSP) location will move from Gunma, Japan to Niigata, Japan. All equipment and most personnel were transferred from the Gunma to the Niigata site. The Niigata site is ISO/IATF16949 certified.				
Reliability Data Summary:	QV DEVICE NAME: LC051281XA PACKAGE: WLCSP8 1.01x1.11 mm				
	Test	Specification	Condition	Interval	Results
	HTOL	JESD22-A108	Ta=125°C (Tj=125°C) , 100 % max rated Vcc	1008 hrs	0/231
	HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/231
	TC	JESD22-A104	Ta= -40°C to +125°C	500 cyc	0/231
	THB	JESD22-A101	85°C, 85% RH, bias	1008 hrs	0/231
	PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-	-
Electrical Characteristic Summary:	There is no change in the electrical performance. Datasheet specifications remain unchanged.				
List of affected Standard Parts:					
	Part Number	Qualification Vehicle			
	LC051281XA-MH	LC051281XA-MH			